SCAS241A - MARCH 1990 - REVISED APRIL 1996

•	Members of the Texas Instruments <i>Widebus</i> ™ Family	74AC1664		) PACKAGE . PACKAGE W)
•	Independent Registers for A and B Buses	ſ		_
•	Multiplexed Real-Time and Stored Data	1DIR 🛛	$1 \cup $	56 ] 1 <u>0</u> E
٠	Flow-Through Architecture Optimizes	1CLKAB	2 5	55 ] 1CLKBA
	PCB Layout	1SAB [	3 !	54 🛛 1SBA
•	Distributed V <sub>CC</sub> and GND Pin Configurations	GND [		53 🛛 GND
	Minimize High-Speed Switching Noise	1A1 [		52 <b>]</b> 1B1
•	EPIC <sup>™</sup> (Enhanced-Performance Implanted	1A2 🛛		51 <b>[</b> 1B2
	CMOS) 1-µm Process	v <sub>cc</sub> [		50 🛛 V <sub>CC</sub>
•	500-mA Typical Latch-Up Immunity at	1A3 🛛		49 <b>[</b> 1B3
•	125°C	1A4 🛛		48 <b>1</b> 1B4
		1A5 🛛		47 <b>1</b> 1B5
•	Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using			
	25-mil Center-to-Center Pin Spacings and	1A6 L		45 <b>1</b> 1B6
	380-mil Fine-Pitch Ceramic Flat (WD)	1A7 L	-	44 <b>1</b> 1B7
	Packages Using 25-mil Center-to-Center	1A8 [		43 <b>1</b> 188
	Pin Spacings	2A1 [		42 2B1
		2A2 [	-	41 0 2B2
desc	cription	2A3 [		40 2B3
	·			
	The 'AC16646 are 16-bit bus transceivers that	2A4 [		38 2B4
	consist of D-type flip-flops and control circuitry,	2A5 [		37 2B5
	with 3-state outputs arranged for multiplexed	2A6 [		36 2B6
	transmission of data directly from the data bus or			35 V <sub>CC</sub>
	from the internal storage registers. The devices can be used as two 8-bit transceivers or one 16-bit	2A7 [	-	34 2B7
	can be used as two o-bit transcervers of one to-bit	2A8 🛛	24 :	33 🛛 2B8

 2A8
 124
 33
 2B8

 GND
 25
 32
 GND

 2SAB
 26
 31
 2SBA

 2CLKAB
 27
 30
 2CLKBA

 2DIR
 28
 29
 2OE

Output-enable ( $\overline{OE}$ ) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both. The select controls (SAB and SBA) can multiplex stored and real-time (transparent mode) data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. DIR determines which bus receives data when  $\overline{OE}$  is active (low). In the isolation mode ( $\overline{OE}$  high), A data may be stored in one register and/or B data may be stored in the other register.

When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B, may be driven at a time.

The 74AC16646 is packaged in the TI shrink small-outline package, which provides twice the functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16646 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74AC16646 is characterized for operation from –40°C to 85°C.



Figure 1

registers.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC and Widebus are trademarks of Texas Instruments Incorporated.

transceiver. Data on the A or B bus is clocked into

the registers on the low-to-high transition of the

appropriate clock (CLKAB or CLKBA) input.

performed with the bus transceivers and

bus-management functions

illustrates the four fundamental

that

can

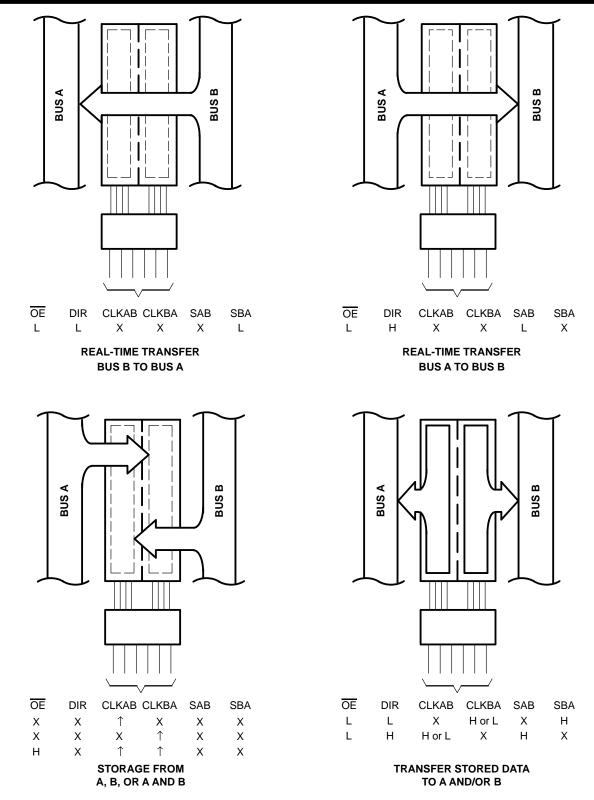
he

UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 1996, Texas Instruments Incorporated

SCAS241A - MARCH 1990 - REVISED APRIL 1996







# 54AC16646, 74AC16646 16-BIT BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS SCAS241A – MARCH 1990 – REVISED APRIL 1996

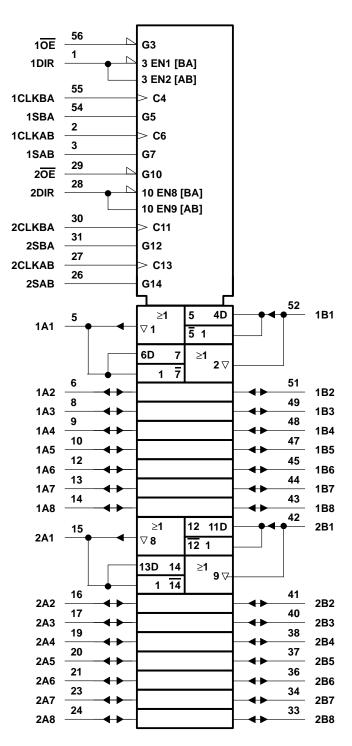
						FUNCTION TAE	BLE	
		INPUTS				DATA	x 1/o†	OPERATION OR FUNCTION
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	OPERATION OR FUNCTION
Х	Х	Ŷ	Х	Х	Х	Input	Unspecified	Store A, B unspecified $^{\dagger}$
Х	Х	Х	$\uparrow$	Х	х	Unspecified	Input	Store B, A unspecified $^{\dagger}$
Н	Х	Ŷ	$\uparrow$	Х	Х	Input	Input	Store A and B data
н	Х	H or L	H or L	Х	Х	Input	Input	Isolation, hold storage
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Х	H or L	Х	н	Output	Input	Stored B data to A bus
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B Bus
L	н	H or L	Х	Н	х	Input	Output	Stored A data to bus

<sup>†</sup> The data-output functions may be enabled or disabled by various signals at OE or DIR. Data-input functions are always enabled, i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



SCAS241A - MARCH 1990 - REVISED APRIL 1996

#### logic symbol<sup>†</sup>

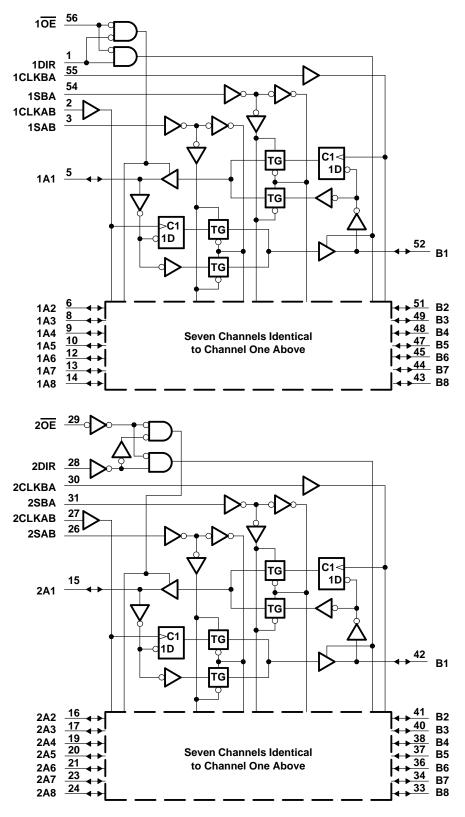


<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



# 54AC16646, 74AC16646 **16-BIT BUS TRANSCEIVERS AND REGISTERS** WITH 3-STATE OUTPUTS SCAS241A – MARCH 1990 – REVISED APRIL 1996

#### logic diagram (positive logic)





SCAS241A - MARCH 1990 - REVISED APRIL 1996

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, VI (see Note 1)	–0.5 V to V <sub>CC</sub> + 0.5 V
Output voltage range, V <sub>O</sub> (see Note 1)	-0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, $I_{IK}$ (V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub> )	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )	±50 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC} \dots $	±50 mA
Continuous current through V <sub>CC</sub> or GND	±400 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): DL package	1.4 W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

#### recommended operating conditions

			54	IAC1664				6	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage (see Note 3)		3	5	5.5	3	5	5.5	V
		V <sub>CC</sub> = 3 V	2.1			2.1			
VIH	High-level input voltage	$V_{CC} = 4.5 V$	3.15			3.15			V
		V <sub>CC</sub> = 5.5 V	3.85			3.85			
		$V_{CC} = 3 V$			0.9			0.9	
VIL	Low-level input voltage	$V_{CC} = 4.5 V$			1.35			1.35	V
		V <sub>CC</sub> = 5.5 V		EL.	1.65			1.65	
٧I	Input voltage		0	PP A	VCC	0		VCC	V
VO	Output voltage		0	C'	VCC	0		VCC	V
		V <sub>CC</sub> = 3 V	4	20	-4			-4	
IОН	High-level output current	V <sub>CC</sub> = 4.5 V	R	)	-24			-24	mA
		V <sub>CC</sub> = 5.5 V	~		-24			-24	
		VCC = 3 V			12			12	
IOL	Low-level output current	$V_{CC} = 4.5 V$			24			24	mA
		V <sub>CC</sub> = 5.5 V			24			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	0		10	ns/V
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All V<sub>CC</sub> and GND pins must be connected to the proper voltage power supply.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



SCAS241A - MARCH 1990 - REVISED APRIL 1996

electrical	characteristics	over	recommended	operating	free-air	temperature	range	(unless
otherwise	noted)					-	•	•

DADAMETED	TEST CONDITIONS		т	4 = 25°C		54AC	16646	74AC1	6646	
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		3 V	2.9			2.9		2.9		
	I <sub>OH</sub> = -50 μA	4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
Maria	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.4		2.48		V
VOH		4.5 V	3.94			3.7		3.8		v
		5.5 V	4.94			4.7		4.8		
	I <sub>OH</sub> = -50 mA <sup>†</sup>	5.5 V				3.85	~			
	I <sub>OH</sub> = -75 mA <sup>†</sup>	5.5 V					IEV,	3.85		
		3 V			0.1		0.1		0.1	
	I <sub>OL</sub> = 50 μA	4.5 V			0.1		<b>Q</b> 0.1		0.1	
		5.5 V			0.1	S)	0.1		0.1	
	I <sub>OL</sub> = 12 mA	3 V			0.36	20	0.5		0.44	
VOL		4.5 V			0.36	22	0.5		0.44	V
		5.5 V			0.36		0.5		0.44	
	I <sub>OL</sub> = 50 mA <sup>†</sup>	5.5 V					1.65			
	I <sub>OL</sub> = 75 mA <sup>†</sup>	5.5 V							1.65	
I	$V_{I} = V_{CC} \text{ or } GND$	5.5 V			±0.1		±1		±1	μΑ
loz‡	$V_{I} = V_{CC}$ or GND	5.5 V			±0.5		±10		±5	μΑ
ICC	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			8		160		80	μΑ
Ci	$V_{I} = V_{CC} \text{ or } GND$	5 V		4.5						pF
Co	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		16						pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms. <sup>‡</sup> For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 2)

		T <sub>A</sub> = 2	25°C	54AC1	6646	74AC1	74AC16646	
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency	0	65	0	65	0	65	MHz
tw	Pulse duration, CLKAB or CLKBA high or low	7		7	N.S.	7		ns
t <sub>su</sub>	Setup time, A before CLKAB↑ or B before CLKBA↑	6.5		6.5	N	6.5		ns
th	Hold time, A after CLKAB $\uparrow$ or B after CLKBA $\uparrow$	1		<b>`</b> ?1		1		ns

# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 2)

		T <sub>A</sub> = 2	25°C	54AC1	6646	74AC1	6646	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency	0	75	0	75	0	75	MHz
tw	Pulse duration, CLKAB or CLKBA high or low	6.5		6.5	h cl	6.5		ns
t <sub>su</sub>	Setup time, A before CLKAB $\uparrow$ or B before CLKBA $\uparrow$	5		5	Nº.	5		ns
th	Hold time, A after CLKAB↑ or B after CLKBA↑	1		9		1		ns

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



SCAS241A - MARCH 1990 - REVISED APRIL 1996

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 2)

	•	7.								
PARAMETER	FROM	то	Т	A = 25°C	;	54AC1	6646	74AC1	UNIT	
FARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			65			65		65		MHz
<sup>t</sup> PLH	A or B	B or A	3.4	9.3	13.2	3.4	15.7	3.4	14.8	ns
<sup>t</sup> PHL	AUB	BUIA	3.6	10	13.4	3.6	15.1	3.6	4.5	115
<sup>t</sup> PZH	OE	A or B	3.8	10.5		3.8	17.6	3.8	16.4	ns
<sup>t</sup> PZL	OE	AUB	4.8	13.9		4.8	22.1	4.8	20.9	115
<sup>t</sup> PHZ		A or B	4.4	7.6		4.4	The second s	4.4	10.7	ns
<sup>t</sup> PLZ	OE	AOIB	4	7		4	10.4	4	10.1	115
<sup>t</sup> PLH	CLKBA or CLKAB	A or B	4.7	12.1		4.7	19.9	4.7	18.7	ns
<sup>t</sup> PHL			4.8	12.2		4.8	18.8	4.8	18	115
<sup>t</sup> PLH	SAB or SBA†	A or B	4.7	12		1 <u>7</u> . 4:	19.9	4.7	18.5	ns
<sup>t</sup> PHL	(with A or B high)	AOIB	4.5	11.4		4.5	17.2	4.5	16.4	115
<sup>t</sup> PLH	SBA or SAB <sup>†</sup>	A or B	4	10.5		4	17.3	4	16.3	ns
<sup>t</sup> PHL	(with A or B low)	AOIB	5.2	13.3		5.2	20.3	5.2	19.3	115
<sup>t</sup> PZH	DIR	A or B	3.6	10.3		3.6	17.9	3.6	16.8	ns
t <sub>PZL</sub>		AUD	4.7	13.5		4.7	22.1	4.7	20.8	115
<sup>t</sup> PHZ	DIR	A or B	4.6	7.8		4.6	11.6	4.6	11.2	ns
<sup>t</sup> PLZ		AUID	3.9	7		3.9	11	3.9	10.6	115

<sup>†</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.

switching characteristics over recommended operating free-air temperature range,	
$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$ (unless otherwise noted) (see Figure 2)	

	FROM	то	T,	4 = 25°C	;	54AC1	6646	74AC1	6646	UNIT
PARAMETER (INPUT)		(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
f <sub>max</sub>			75			75		75		MHz
<sup>t</sup> PLH	A or B	B or A	2.9	5.5	8.5	2.9	10.1	2.9	9.5	ns
<sup>t</sup> PHL	AOIB	DUIA	2.9	5.7	8.9	2.9	10.1	2.9	9.7	115
<sup>t</sup> PZH	OE	A or B	3.1	6.1	9.4	3.1	11.1	3.1	10.5	ns
<sup>t</sup> PZL	UE	A or B	4.1	7.3	11	4.1	12.9	4.1	12.2	115
<sup>t</sup> PHZ	OE	A or B	4	6.1	8.4	4	9.1	4	8.9	ns
<sup>t</sup> PLZ	UE	AOIB	3.8	5.7	8	3.8	8.9	3.8	8.6	115
<sup>t</sup> PLH	CLKBA or CLKAB	A or B	3.9	7	10.8	3.9	12.8	3.9	12.1	ns
<sup>t</sup> PHL			3.9	7.1	10.8	3.9	12.5	3.9	11.9	115
<sup>t</sup> PLH	SAB or SBA†	A or B	4	7.4	11.1	A	13.4	4	12.5	ns
<sup>t</sup> PHL	(with A or B high)	AUD	3.6	6.7	10.2	3.6	11.8	3.6	11.2	115
<sup>t</sup> PLH	SBA or SAB <sup>†</sup>	A or B	3.3	6.1	9.5	3.3	11.2	3.3	10.6	ns
<sup>t</sup> PHL	(with A or B low)	AUB	4.3	8	11.7	4.3	13.9	4.3	13.1	115
<sup>t</sup> PZH	DIR	A or B	3	5.9	9.6	3	11.6	3	10.9	ns
<sup>t</sup> PZL			3.6	7	11.1	3.6	12.9	3.6	12.2	115
<sup>t</sup> PHZ	DIR	A or B	4	6.2	8.8	4	9.6	3	9.4	ns
<sup>t</sup> PLZ		A or B	3.7	5.7	8.2	3.7	9	3.7	8.8	115

<sup>†</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.

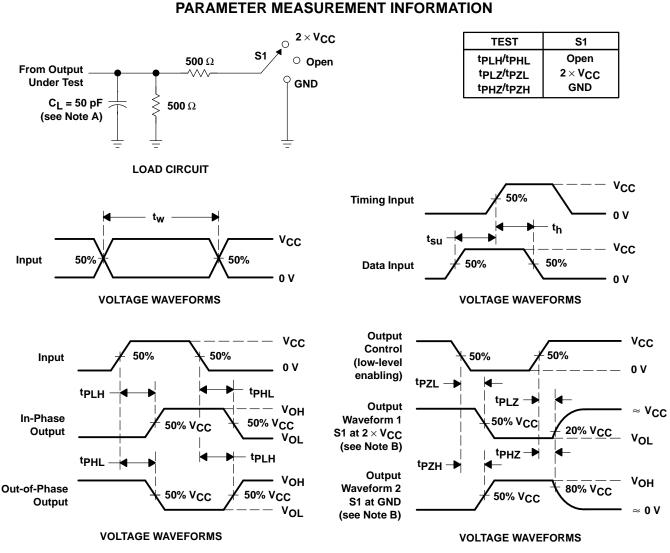
PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



SCAS241A - MARCH 1990 - REVISED APRIL 1996

### operating characteristics, $V_{CC} = 5 V$ , $T_A = 25^{\circ}C$

	PARAMETER	TEST CO	TYP	UNIT		
<u> </u>	Dower dissinction conscitance	Outputs enabled	C <sub>1</sub> = 50 pF,	f = 1 MHz	62	pF
Cpd	Power dissipation capacitance	Outputs disabled	C[ = 50 pF,		14	рг



- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub> = 3 ns, t<sub>f</sub> = 3 ns.
  - D. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms



#### **IMPORTANT NOTICE**

Texas Instruments (TI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

TI warrants performance of its semiconductor products and related software to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Certain applications using semiconductor products may involve potential risks of death, personal injury, or severe property or environmental damage ("Critical Applications").

TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS.

Inclusion of TI products in such applications is understood to be fully at the risk of the customer. Use of TI products in such applications requires the written approval of an appropriate TI officer. Questions concerning potential risk applications should be directed to TI through a local SC sales office.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards should be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor does TI warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

Copyright © 1996, Texas Instruments Incorporated